

Dual Complementary General Purpose Transistor NST3946DP6T5G

The NST3946DP6T5G device is a spin-off of our popular SOT-23/SOT-323/SOT-563 three-leaded device. It is designed for general purpose amplifier applications and is housed in the SOT-963 six-leaded surface mount package. By putting two discrete devices in one package, this device is ideal for low-power surface mount applications where board space is at a premium.

Features

- h_{FE}, 100-300
- Low $V_{CE(sat)}$, $\leq 0.4 \text{ V}$
- Reduces Board Space and Component Count
- NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free and are RoHS Compliant

MAXIMUM RATINGS

Rating		Symbol	Value	Unit
Collector - Emitter Voltage		V_{CEO}	40	Vdc
Collector - Base Voltage		V_{CBO}	60	Vdc
Emitter – Base Voltage		V _{EBO}	6.0	Vdc
Collector Current - Continuous		Ic	200	mAdc
Electrostatic Discharge	HBM MM	ESD Class	2 B	

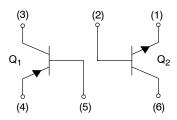
THERMAL CHARACTERISTICS

Characteristic (Single Heated)	Symbol	Max	Unit
Total Device Dissipation T _A = 25°C Derate above 25°C (Note 2)	P _D	240 1.9	mW mW/°C
Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{\theta JA}$	520	°C/W
Total Device Dissipation T _A = 25°C Derate above 25°C (Note 3)	P _D	280 2.2	mW mW/°C
Thermal Resistance, Junction-to-Ambient (Note 3)	$R_{\theta JA}$	446	°C/W
Characteristic (Dual Heated) (Note 4)	Symbol	Max	Unit
Total Device Dissipation T _A = 25°C Derate above 25°C (Note 2)	P _D	350 2.8	mW mW/°C
Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{\theta JA}$	357	°C/W
Total Device Dissipation T _A = 25°C Derate above 25°C (Note 3)	P _D	420 3.4	mW mW/°C
Thermal Resistance, Junction-to-Ambient (Note 3)	$R_{\theta JA}$	297	°C/W
Junction and Storage Temperature Range	T _J , T _{stg}	-55 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- 2. FR-4 @ 100 mm², 1 oz. copper traces, still air 3. FR-4 @ 500 mm², 1 oz. copper traces, still air.
- 4. Dual heated values assume total power is sum of two equally powered channels

1



NST3946DP6T5G*

*Q1 PNP Q2 NPN



CASE 527AD

MARKING DIAGRAM



= Device Code

(180° Clockwise Rotation)

= Date Code

ORDERING INFORMATION

Device	Package	Shipping [†]
NST3946DP6T5G	SOT-963 (Pb-Free)	8000 / Tape & Reel

DISCONTINUED (Note 1)

NSVT3946DP6T5G	SOT-963	8000 /
	(Pb-Free)	Tape & Reel

- †For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.
- 1. DISCONTINUED: This device is not recommended for new design. Please contact your **onsemi** representative for information. The most current information on this device may be available on www.onsemi.com.

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic	_	Symbol	Min	Max	Unit
OFF CHARACTERISTICS					
Collector – Emitter Breakdown Voltage (Note 5) ($I_C = 1.0$ mAdc, $I_B = 0$) ($I_C = -1.0$ mAdc, $I_B = 0$)	(NPN) (PNP)	V _(BR) CEO	40 -40		Vdc
Collector – Base Breakdown Voltage ($I_C = 10 \mu Adc, I_E = 0$) ($I_C = -10 \mu Adc, I_E = 0$)	(NPN) (PNP)	V _(BR) CBO	60 -40	-	Vdc
Emitter – Base Breakdown Voltage $ (I_E = 10 \; \mu \text{Adc}, \; I_C = 0) \\ (I_E = -10 \; \mu \text{Adc}, \; I_C = 0) $	(NPN) (PNP)	V _{(BR)EBO}	6.0 -5.0	- -	Vdc
Collector Cutoff Current ($V_{CE} = 30 \text{ Vdc}$, $V_{EB} = 3.0 \text{ Vdc}$) ($V_{CE} = -30 \text{ Vdc}$, $V_{EB} = -3.0 \text{ Vdc}$)	(NPN) (PNP)	I _{CEX}	- -	50 –50	nAdc
ON CHARACTERISTICS (Note 5)					
DC Current Gain $ \begin{aligned} &(I_C = 0.1 \text{ mAdc, } V_{CE} = 1.0 \text{ Vdc}) \\ &(I_C = 1.0 \text{ mAdc, } V_{CE} = 1.0 \text{ Vdc}) \\ &(I_C = 10 \text{ mAdc, } V_{CE} = 1.0 \text{ Vdc}) \\ &(I_C = 50 \text{ mAdc, } V_{CE} = 1.0 \text{ Vdc}) \\ &(I_C = 100 \text{ mAdc, } V_{CE} = 1.0 \text{ Vdc}) \end{aligned} $	(NPN)	h _{FE}	40 70 100 60 30	- - 300 - -	-
$ \begin{array}{l} (I_{C}=-0.1 \text{ mAdc, } V_{CE}=-1.0 \text{ Vdc}) \\ (I_{C}=-1.0 \text{ mAdc, } V_{CE}=-1.0 \text{ Vdc}) \\ (I_{C}=-10 \text{ mAdc, } V_{CE}=-1.0 \text{ Vdc}) \\ (I_{C}=-50 \text{ mAdc, } V_{CE}=-1.0 \text{ Vdc}) \\ (I_{C}=-100 \text{ mAdc, } V_{CE}=-1.0 \text{ Vdc}) \end{array} $	(PNP)		60 80 100 60 30	- 300 - -	
Collector – Emitter Saturation Voltage ($I_C = 10 \text{ mAdc}$, $I_B = 1.0 \text{ mAdc}$) ($I_C = 50 \text{ mAdc}$, $I_B = 5.0 \text{ mAdc}$)	(NPN)	V _{CE(sat)}	- -	0.2 0.3	Vdc
$(I_C = -10 \text{ mAdc}, I_B = -1.0 \text{ mAdc})$ $(I_C = -50 \text{ mAdc}, I_B = -5.0 \text{ mAdc})$	(PNP)		- -	-0.25 -0.4	
Base – Emitter Saturation Voltage (I_C = 10 mAdc, I_B = 1.0 mAdc) (I_C = 50 mAdc, I_B = 5.0 mAdc)	(NPN)	V _{BE(sat)}	0.65 -	0.85 0.95	Vdc
$(I_C = -10 \text{ mAdc}, I_B = -1.0 \text{ mAdc})$ $(I_C = -50 \text{ mAdc}, I_B = -5.0 \text{ mAdc})$	(PNP)		-0.65 -	-0.85 -0.95	

^{5.} Pulse Test: Pulse Width \leq 300 $\mu s;$ Duty Cycle \leq 2.0%.

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted) (Continued)

Characteristic			Symbol	Min	Max	Unit	
SMALL-SIGNAL	CHARACTERISTICS						
Current – Gain – Bandwidth Product ($I_C = 10 \text{ mAdc}$, $V_{CE} = 20 \text{ Vdc}$, $f = 100 \text{ MHz}$) ($I_C = -10 \text{ mAdc}$, $V_{CE} = -20 \text{ Vdc}$, $f = 100 \text{ MHz}$)		(NPN) (PNP)	f _T	200 250	- -	MHz	
Output Capacitance $(V_{CB} = 5.0 \text{ Vdc}, I_E = 0, f = 1.0 \text{ MHz})$ $(V_{CB} = -5.0 \text{ Vdc}, I_E = 0, f = 1.0 \text{ MHz})$		(NPN) (PNP)	C _{obo}	- -	4.0 4.5	pF	
Input Capacitance $(V_{EB} = 0.5 \text{ Vdc}, I_C = 0, f = 1.0 \text{ MHz})$ $(V_{EB} = -0.5 \text{ Vdc}, I_C = 0, f = 1.0 \text{ MHz})$		(NPN) (PNP)	C _{ibo}	- -	8.0 10.0	pF	
Noise Figure $(V_{CE} = 5.0 \text{ Vdc}, I_{C} = 100 \mu\text{Adc}, R_{S} = 1.0 k \Omega, f = 1.0 k\text{Hz})$ $(V_{CE} = -5.0 \text{ Vdc}, I_{C} = -100 \mu\text{Adc}, R_{S} = 1.0 k \Omega, f = 1.0 k\text{Hz})$		(NPN) (PNP)	NF	- -	5.0 4.0	dB	
SWITCHING CHA	ARACTERISTICS						
Delay Time	$(V_{CC} = 3.0 \text{ Vdc}, V_{BE} = -0.5 \text{ Vdc})$ $(V_{CC} = -3.0 \text{ Vdc}, V_{BE} = 0.5 \text{ Vdc})$	(NPN) (PNP)	t _d	- -	35 35		
Rise Time	$(I_C = 10 \text{ mAdc}, I_{B1} = 1.0 \text{ mAdc})$ $(I_C = -10 \text{ mAdc}, I_{B1} = -1.0 \text{ mAdc})$	(NPN) (PNP)	t _r	- -	35 35	ns	
Storage Time	$(V_{CC} = 3.0 \text{ Vdc}, I_{C} = 10 \text{ mAdc})$ $(V_{CC} = -3.0 \text{ Vdc}, I_{C} = -10 \text{ mAdc})$	(NPN) (PNP)	t _s	- -	275 250		
Fall Time	$(I_{B1} = I_{B2} = 1.0 \text{ mAdc})$ $(I_{B1} = I_{B2} = -1.0 \text{ mAdc})$	(NPN) (PNP)	t _f	- -	50 50	ns	

NPN TRANSISTOR

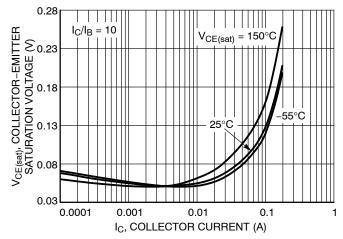


Figure 1. Collector Emitter Saturation Voltage vs. Collector Current

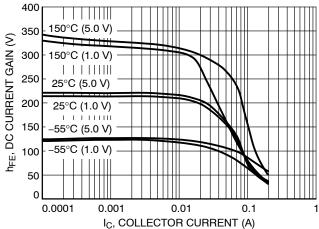


Figure 2. DC Current Gain vs. Collector Current

NPN TRANSISTOR

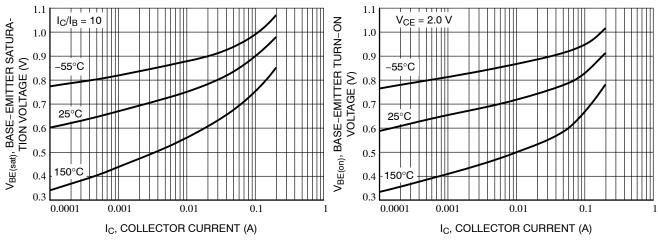


Figure 3. Base Emitter Saturation Voltage vs.
Collector Current

Figure 4. Base Emitter Turn-On Voltage vs.
Collector Current

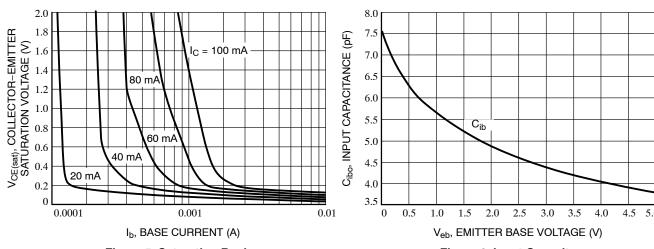


Figure 5. Saturation Region

Figure 6. Input Capacitance

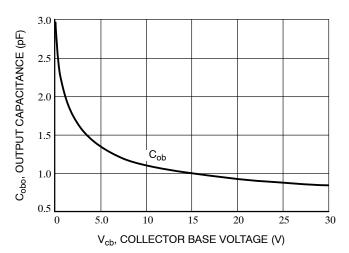


Figure 7. Output Capacitance

PNP TRANSISTOR

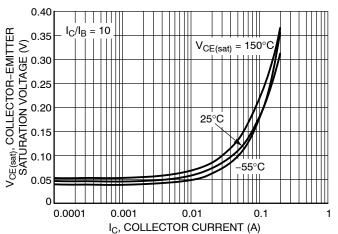


Figure 8. Collector Emitter Saturation Voltage vs. Collector Current

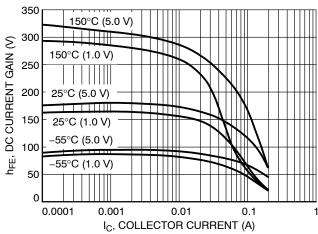


Figure 9. DC Current Gain vs. Collector Current

PNP TRANSISTOR

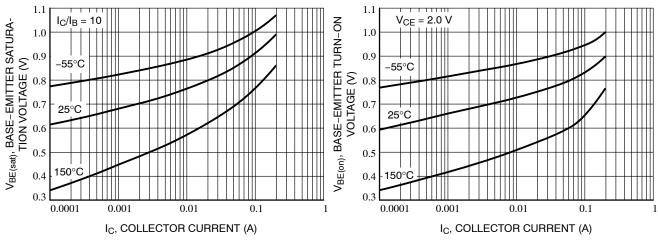


Figure 10. Base Emitter Saturation Voltage vs.
Collector Current

Figure 11. Base Emitter Turn-On Voltage vs.
Collector Current

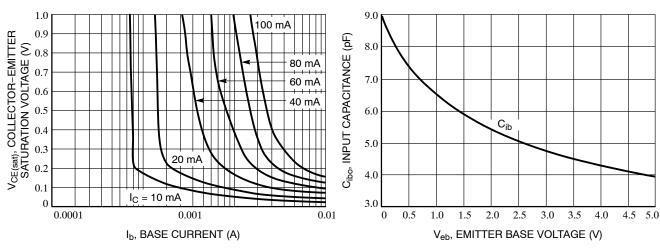


Figure 12. Saturation Region

Figure 13. Input Capacitance

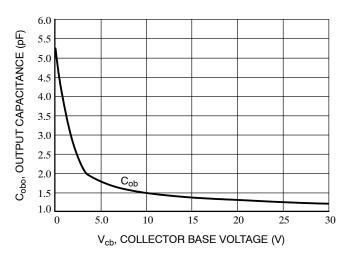


Figure 14. Output Capacitance





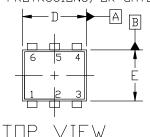


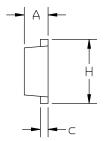
SOT-963 1.00x1.00x0.37, 0.35P CASE 527AD **ISSUE F**

DATE 20 FEB 2024

NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2018. 1.
- CONTROLLING DIMENSION: MILLIMETERS.
- MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS, MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
 DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH,
- PROTRUSIONS, OR GATE BURRS

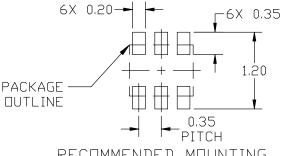




VIFW



	MILLIMETERS		
DIM	MIN.	N□M.	MAX.
А	0.34	0.37	0.40
b	0.10	0.15	0.20
C	0.07	0.12	0.17
D	0.95	1.00	1.05
E	0.75	0.80	0.85
е	0.35 BSC		
Н	0.95	1.00	1.05
L	0.19 REF		
L2	0.05	0.10	0.15



RECOMMENDED MOUNTING FOOTPRINT

*For additional information on our Pb-Free strategy and soldering details, please download the $\ensuremath{\square N}$ Semiconductor Soldering and Mounting Techniques Reference manual, SOLDERRM/D.

BUTTUM VIEW

STYLE 1:	STYLE 2:	STYLE 3:
PIN 1. EMITTER 1	PIN 1. EMITTER 1	PIN 1. CATHODE 1
2. BASE 1	EMITTER2	CATHODE 1
COLLECTOR 2	3. BASE 2	ANODE/ANODE 2
4. EMITTER 2	COLLECTOR 2	CATHODE 2
5. BASE 2	5. BASE 1	CATHODE 2
COLLECTOR 1	COLLECTOR 1	6. ANODE/ANODE 1
STYLE 4:	STYLE 5:	STYLE 6:

PIN 1. CATHODE 2. CATHODE 3. ANODE 4. ANODE PIN 1. COLLECTOR 2. COLLECTOR 3. BASE 4. EMITTER

PIN 1. CATHODE 2. ANODE 3. CATHODE 4. CATHODE 5 CATHODE CATHODE 6. CATHODE 6. CATHODE

5. COLLECTOR 6. COLLECTOR STYLE 8: PIN 1. DRAIN 2. DRAIN STYLE 7: PIN 1. CATHODE 2. ANODE 3. CATHODE 4. CATHODE 3. GATE 4. SOURCE 5. ANODE 6. CATHODE 5. DRAIN 6. DRAIN 5. GATE 2 6. DRAIN 1

STYLE 9: PIN 1. SOURCE 1 2. GATE 1 3. DRAIN 2 4. SOURCE 2

GENERIC MARKING DIAGRAM*



XX = Specific Device Code = Month Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "=", may or may not be present. Some products may not follow the Generic Marking.

DOCUMENT NUMBER:	98AON26456D	Electronic versions are uncontrolled except when accessed directly from the Docume Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in rec	
DESCRIPTION:	SOT-963 1.00x1.00x0.37, 0.35P		PAGE 1 OF 1

onsemi and Onsemi are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries, onsemi reserves the right to make changes without further notice to any products herein. **onsemi** makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does **onsemi** assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. onsemi does not convey any license under its patent rights nor the rights of others.

STYLE 10: PIN 1. CATHODE 1 2. N/C 3. CATHODE 2

4. ANODE 2

5. N/C 6. ANODE 1

onsemi, Onsemi, and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "onsemi" or its affiliates and/or subsidiaries in the United States and/or other countries. onsemi owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of onsemi's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. Onsemi reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and onsemi makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using onsemi products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by onsemi. "Typical" parameters which may be provided in onsemi data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. onsemi does not convey any license under any of its intellectual property rights nor the rights of others. onsemi products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA class 3 medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase

ADDITIONAL INFORMATION

TECHNICAL PUBLICATIONS:

 $\textbf{Technical Library:} \ \underline{www.onsemi.com/design/resources/technical-documentation}$

onsemi Website: www.onsemi.com

ONLINE SUPPORT: www.onsemi.com/support

For additional information, please contact your local Sales Representative at

www.onsemi.com/support/sales